

DUAL STACKED DIE PACKAGE

ABSTRACT OF THE DISCLOSURE

A semiconductor device including a leadframe and two stacked dies, a first of which is on a top surface of a leadframe while the second one is on a bottom surface of the leadframe. The drain region of the first die is coupled to a drain clip assembly that includes a drain clip that is in contact with a lead rail. The body of the semiconductor device includes a window or opening that exposes the drain region of the second die.

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